

Application Serial No. 10/750,580
Response dated September 9, 2005
Reply to Restriction Requirement dated August 10, 2005

Amendments to Claims

This listing of claims will replace all prior versions and listing of claims in the application:

Listing of Claims

1. (original) An integrated package comprising:
 - a first wafer having a first surface;
 - a second wafer having a first surface bonded at a first perimeter to the first surface of the first wafer; and
 - a recess formed in the first surface of the first wafer in a second perimeter situated within the first perimeter.
2. (original) The package of claim 1, further comprising a first bump pattern in the first surface of the first wafer within the second perimeter.
3. (original) The package of claim 2, further comprising a second bump pattern on a second surface of the first wafer.
4. (original) The package of claim 3, further comprising a seal between the first and second wafers at the first

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perimeter.

5. (original) The package of claim 4, wherein the seal comprises:

a spacer material; and
a layer of malleable material.

6. (original) The package of claim 5, wherein the seal further comprises a layer of bondable material.

7. (original) The package of claim 6, further comprising structural supports in the recess of the first wafer.

8. (original) The package of claim 7, further comprising at least one pumpout opening in the first wafer.

9. (original) The package of claim 8, wherein the first and second wafers comprise silicon.

10-25. (canceled)

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26. (currently amended) An integral package comprising:
- a first wafer comprising:
- a seal along a first perimeter on a first surface
 of the first wafer; and
- a trench in the first surface of the first wafer
 along a second perimeter within the first
 perimeter; and
- a second wafer having a first surface bonded to the
 [[second]] first wafer along the seal.
27. (original) The package of claim 26, wherein the first
wafer further comprises an anti-reflective pattern on the
first surface.
28. (original) The package of claim 27, wherein the first
wafer further comprises at least one vent hole and vent
hole seal.
29. (original) The package of claim 28, wherein the seal
comprises a spacer material.

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30. (original) The package of claim 29, wherein the first wafer further comprises an anti-reflective pattern on a second surface.